	CONNECTING CONNECTING CONNECTING COPyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both	This docume level parts, th	ent is a declarat he declaration e	ion of the sencompasse	substances es all lowe	within the 1 r level mate	nanufacture rials for wh	er listed ite	em. Note: anufacture	if the item is an as er has engineering	sembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplie	r Information														
Company name* Company unique ID					l	Unique ID Authority					Response Date*				
onsemi											2024-04-24				
Contact N	lame		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-	Env-Stewards	Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	e Date Version Manufacturing Site		ng Site	V	Veight*	UOM	Unit Type		
		STK672-642AN-E Stepping motor driv		river		2024-04-24		1	VN2		3	380.0	mg	Each	
/Ianufa	cturing Proccess Information	tion													
	Terminal Plating / Grid Array Material		erminal Base	Alloy	J-STD-020 MSL R		Peak Proc	eak Process Body Temperatu		ure Max Time at Peak Tem		Temperatu	ire Num	ber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy		CU Alloy]	NA		0		С	30		second	ls 3			
omments	8														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to ha			ice drop-dowi	n. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature R	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	1117.12	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	_	6.3676	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		42.4506	mg
			В	Nickel (Ni)	7440-02-0		2.0108	mg
			Supplier	Acrylic resins	Proprietary Data		0.782	mg
			Supplier	Copper (Cu)	7440-50-8		39.6578	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.6703	mg
			Supplier	Aluminum (Al)	7429-90-5		1025.181	mg
Chip Parts	28.99	mg	Supplier	Silver (Ag)	7440-22-4		0.2087	mg
			Supplier	Epoxy resins	129915-35-1		0.0203	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0319	mg
			Supplier	Tin (Sn)	7440-31-5		0.89	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.1826	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.3653	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		4.8964	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0232	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0058	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		18.945	mg
			В	Nickel (Ni)	7440-02-0		1.4031	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.0319	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0058	mg
			Supplier	Copper (Cu)	7440-50-8		1.7829	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.1971	mg
lie	8.03	mg	Supplier	Silicon (Si)	7440-21-3		8.0204	mg
			Supplier	Polyimide	Proprietary Data		0.0096	mg
ead Frame	463.27	mg	Supplier	Tin (Sn)	7440-31-5		0.278	mg
			Supplier	Copper (Cu)	7440-50-8		462.992	mg
Iold Compound-Black	1717.18	mg		Brominated epoxy resin	proprietary data		34.3436	mg
			Supplier	Phenolic Resin	Proprietary Data		120.2026	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.3436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1202.026	mg

			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	326.2642	mg
Plating	0.93	mg	Supplier	Tin (Sn)	7440-31-5	0.5758	mg
			В	Nickel (Ni)	7440-02-0	0.3542	mg
Solder Ball	43.16	mg	Supplier	Silver (Ag)	7440-22-4	1.3423	mg
			Supplier	Tin (Sn)	7440-31-5	41.4983	mg
			В	Antimony (Sb)	7440-36-0	0.0043	mg
			Supplier	Copper (Cu)	7440-50-8	0.3151	mg
Wire Bond	1.32	mg	Supplier	Silicon (Si)	7440-21-3	0.0046	mg
			Supplier	Aluminum (Al)	7429-90-5	1.3154	mg